

## Applications:



VR/AR



Wearable Earbuds



Smarthome



P= 0.3mm



Ultra Low Profile



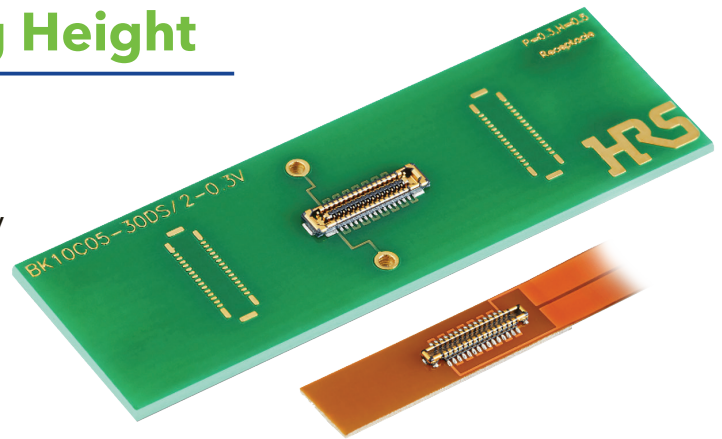
Full Armored

**Patented**

## 0.3mm Pitch, 0.5mm Stacking Height

### Fully Armored, Hybrid FPC-to-Board Connector

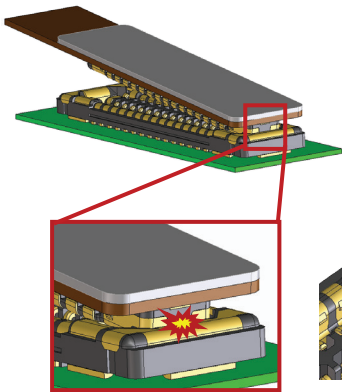
- Ultra low-profile design with high power supply capacity
  - Stacking Height: 0.5mm, Depth: 1.7mm
  - Rated Current: Power contact 5A, Signal contact 0.3A
- Fully armored design ensures high durability
- Dimpled lock design on contacts enables high extraction force
- Easy mating operation with wide self alignment range
  - Pitch Direction:  $\pm 0.29\text{mm}$
  - Width Direction:  $\pm 0.24\text{mm}$
- Multi-point soldering enhances PCB peeling strength



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**Sample Number:**  
**US-BK10SAMPLE-22**

#### Fully Armored Design

**Significant Reduction in Housing Damage Due to Misalignment**

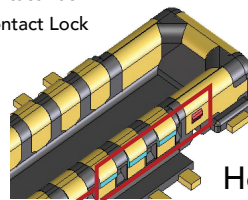


All Mating Surfaces covered in metal

#### Dimple for Lock Design on the Contacts

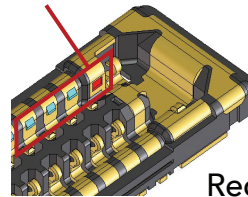
**Achieves High Extraction Force**

- Signal Contact Lock
- Power Contact Lock



Header

Contact Lock



Receptacle

#### Specifications

Rated Current	Power Contact: 5A Signal Contact: 0.3A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +85°C*
Contact Resistance	Power Contact: 30mΩ Max. Signal Contact: 50mΩ Max.
Withstanding Voltage	100V AC for 1 min.
Insulation Resistance	50MΩ min. (100V DC)
Mating Durability	10 times

\*Includes the temperature rise due to current flow.  
 No. of Pos.:30pos.



For additional information please go to [www.hirose.com/product/series/BK10](http://www.hirose.com/product/series/BK10)  
 Specifications herein are subject to change without notice.  
 Contact Hirose for latest specifications, drawings, or availabilities.

STAY CONNECTED

